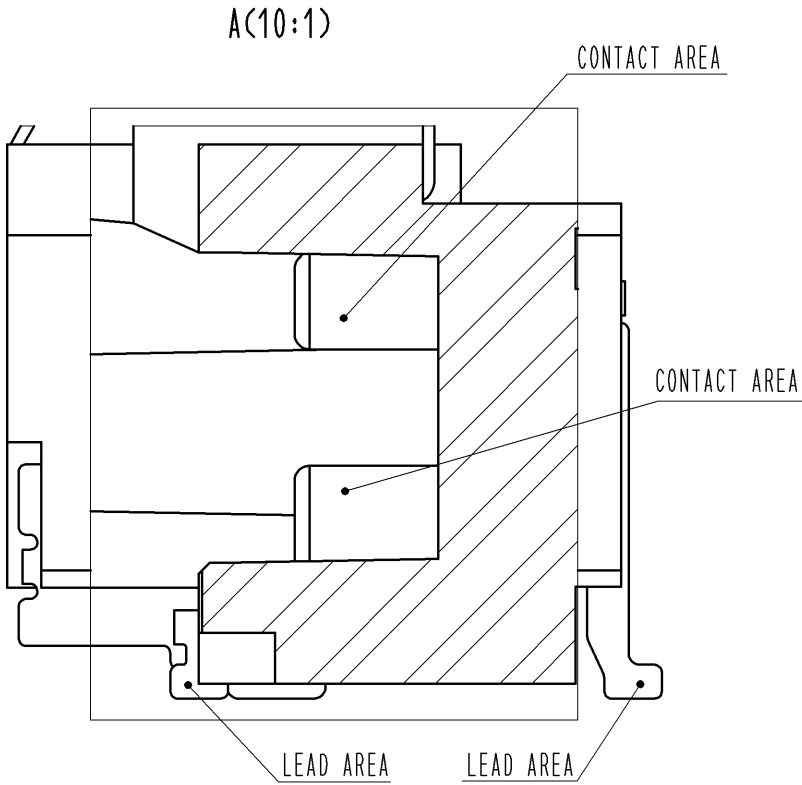
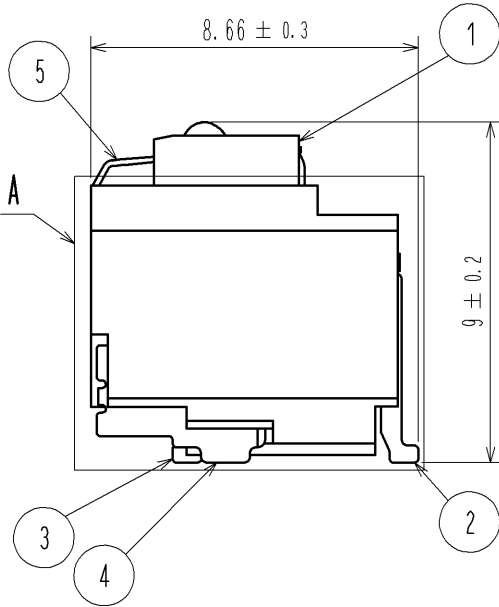
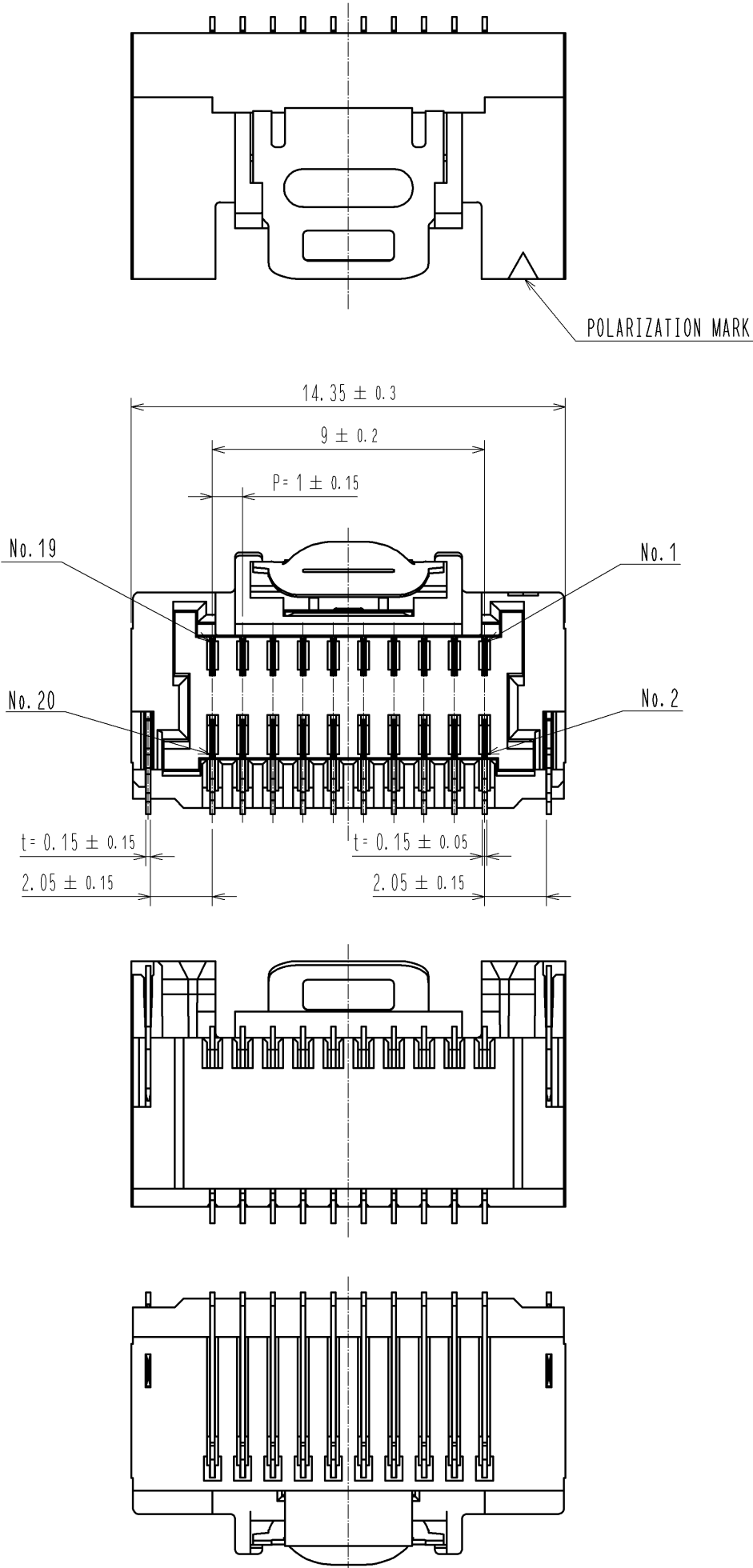
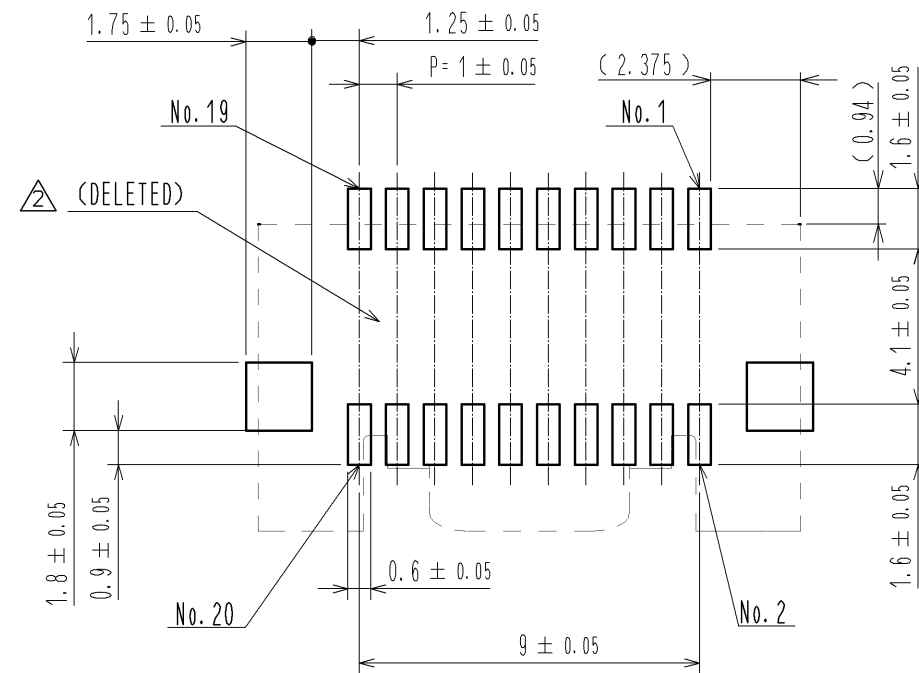




NOTE 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
2. (DELETED)
TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MONUTED TO FPC.

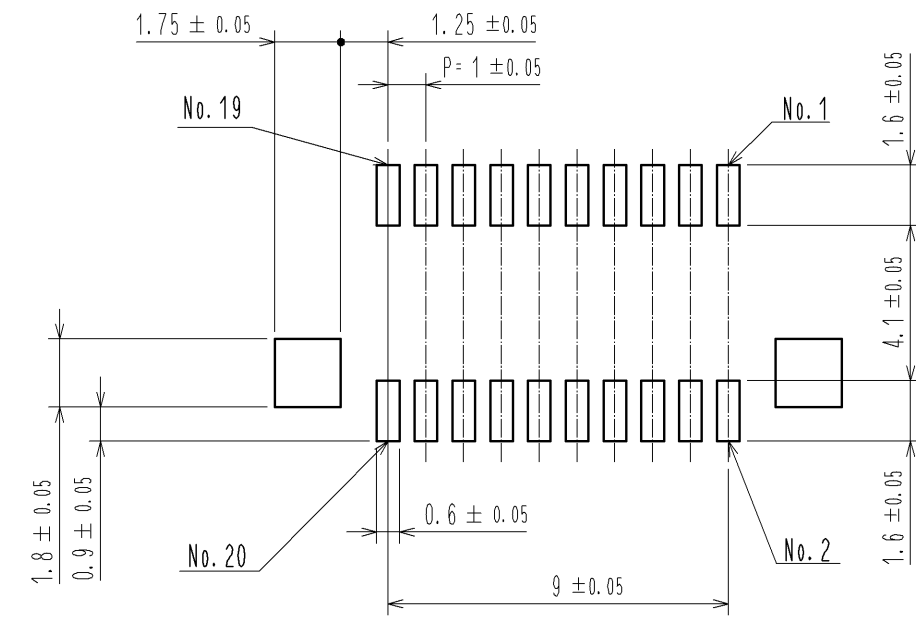
3	BRASS	CONTACT AREA : Au PLATING 0.05 μ m MIN LEAD AREA : Au PLATING 0.05 μ m MIN UNDER PLATING : Ni PLATING 1 μ m MIN	8	PS	REEL, BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05 μ m MIN LEAD AREA : Au PLATING 0.05 μ m MIN UNDER PLATING : Ni PLATING 1 μ m MIN	7	POLYESTER	CLEAR
1	LCP	BLACK, UL94V-0	6	PS	CLEAR
NO. MATERIAL FINISH, REMARKS			5	STAINLESS STEEL	—
			4	BRASS	CONTACT AREA : Sn PLATING 1 μ m MIN UNDER PLATING : Ni PLATING 0.5 μ m MIN
NO. MATERIAL FINISH, REMARKS					
UNITS mm		SCALE 5 : 1	COUNT 2	DESCRIPTION OF REVISIONS DIS-H-008701	
DESIGNED MI. SAKIMURA		CHECKED TS. KUMAZAWA		DATE 14. 04. 22	
APPROVED : KI. AKIYAMA		11. 12. 26		DRAWING NO. EDC3-332132-01	
CHECED : OM. MIYAMOTO		11. 12. 26		PART NO. DF50-20DP-1H(51)	
DESIGNED : TT. OHSAKO		11. 12. 01		CODE NO. CL665-0016-5-51	
DRAWN : TT. OHSAKO		11. 12. 01			

RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE) (FREE)

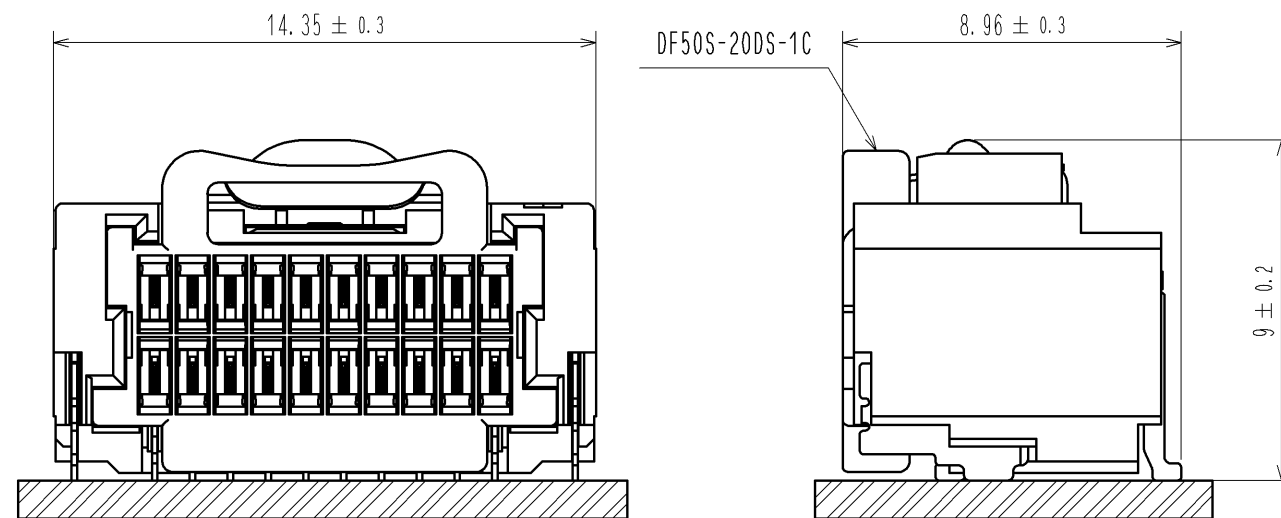


RECOMMENDED METAL MASK (FREE)

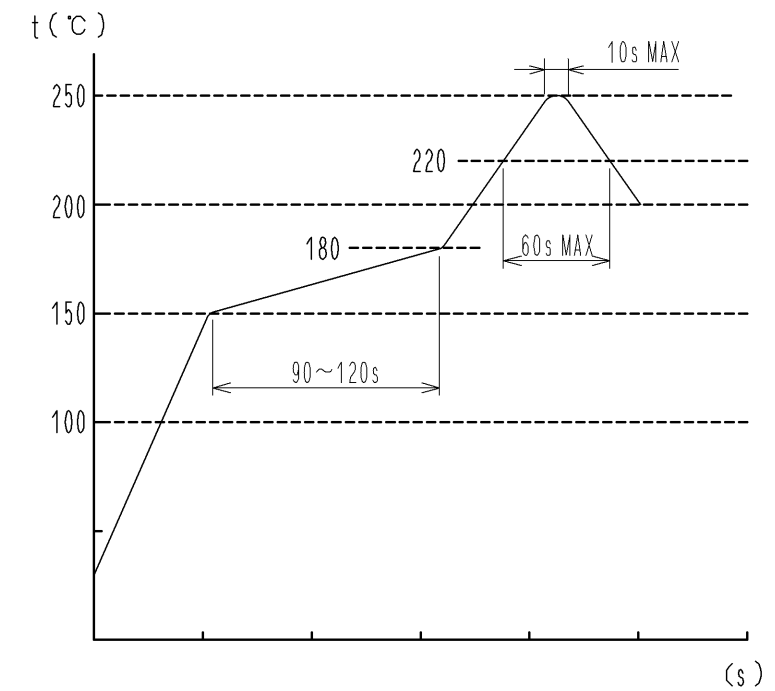
THICKNESS : 0.1mm
OPEN AREA RATIO:100%



MATING FIGURE (5 : 1)



REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



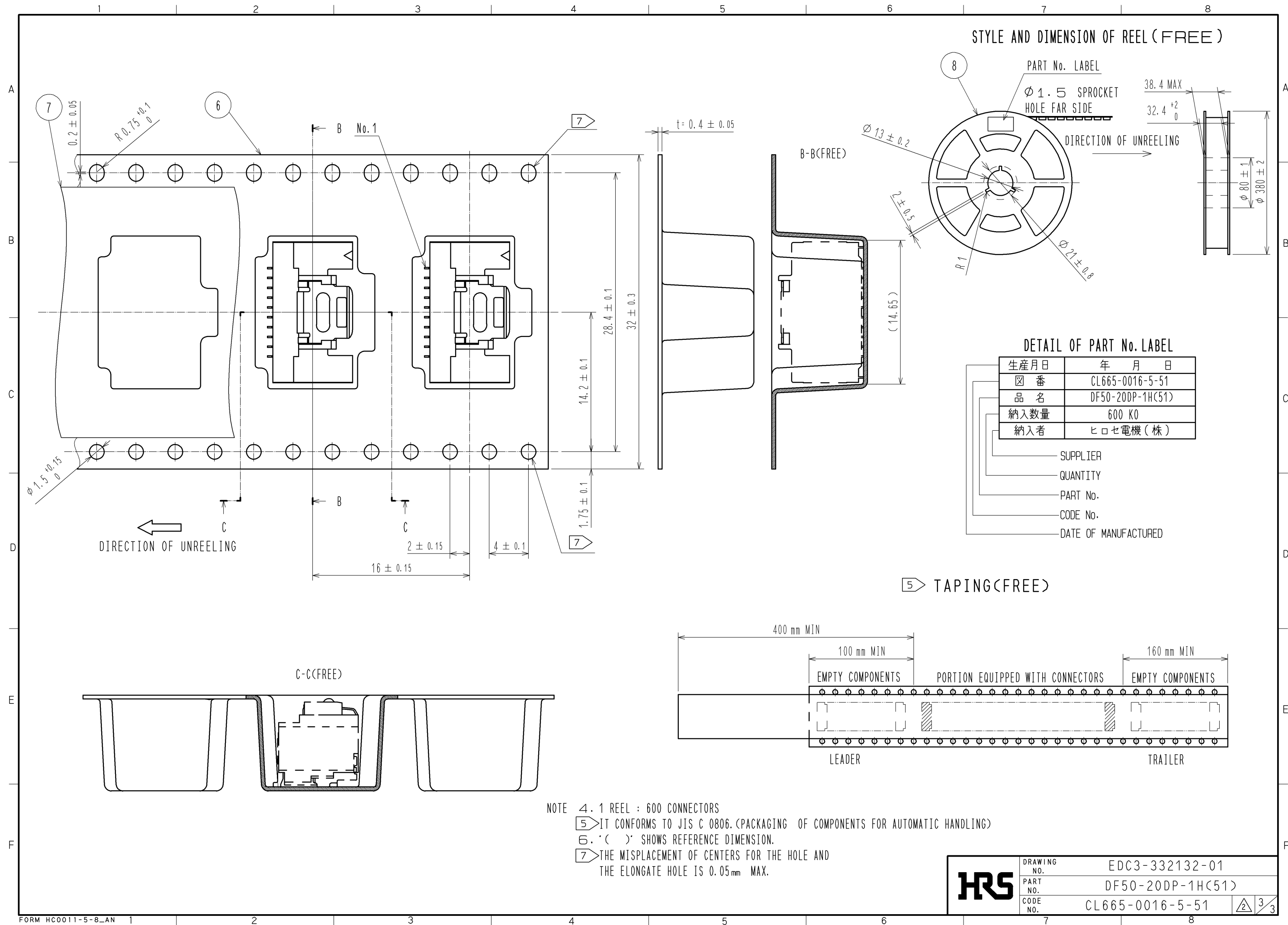
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING MATERIAL etc..

HRS

DRAWING NO.	EDC3-332132-01
PART NO.	DF50-20DP-1H(51)
CODE NO.	CL665-0016-5-51

2/3

**HRS**

DRAWING NO.	EDC3-332132-01
PART NO.	DF50-20DP-1H(51)
CODE NO.	CL665-0016-5-51

2	3	3
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